



**DO41 GPP Axial-leaded Rectifier**

<b>Material Content Declaration</b>					
<b>Material name</b>	<b>Substance name, e.g. Copper (Cu), Gold (Au)</b>	<b>CAS no., if known</b>	<b>Substance mass (mg)</b>	<b>% OF Weight (%)</b>	<b>ppm Of Total Weight</b>
<b>Lead Wire</b> <b>64.93%</b>	Copper (Cu)	7440-50-8	218.061	99.9786	649,218.4
	Phosphorus (P)	7723-14-0	0.002	0.0010	6.5
	Arsenic (As)	7440-38-2	0.002	0.0010	6.5
	Tin (Sn)	7440-31-5	0.002	0.0010	6.5
	Oxygen (O)	7782-44-7	0.001	0.0005	3.2
	Sulfur (S)	7704-34-9	0.026	0.0120	77.9
	Iron (Fe)	7439-89-6	0.001	0.0007	4.3
	Nickel (Ni)	7440-02-0	0.001	0.0003	1.9
	Bismuth (Bi)	7440-69-9	0.004	0.0020	13.0
	Antimony (Sb)	1309-64-4	0.004	0.0020	13.0
	Lead (Pb)	7439-92-1	0.001	0.0006	3.9
	Zinc (Zn)	7440-66-6	0.001	0.0003	1.9
	<b>Total</b>			<b>218.11</b>	
<b>Solder Wafer</b> <b>0.59%</b>	Lead (Pb)	7439-92-1	1.83	92.51	5,445.3
	Tin (Sn)	7440-31-5	0.10	5.01	294.7
	Silver (Ag)	7440-22-4	0.05	2.48	145.9
<b>Total</b>			<b>1.98</b>		
<b>Chip</b> <b>0.94%</b>	Silicon (Si)	7440-21-3	3.16	100.00	9,402.1
	<b>Total</b>			<b>3.16</b>	
<b>Molding</b> <b>33.27%</b>	Epoxy	25928-94-3	111.74	100.00	332,675.4
	<b>Total</b>			<b>111.74</b>	
<b>Plating</b> <b>0.27%</b>	Tin (Sn)	7440-31-5	0.90	100.00	2,679.5
	<b>Total</b>			<b>0.90</b>	
<b>Total mass (mg)</b>			<b>335.88</b>		